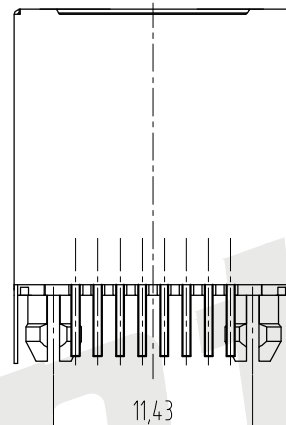
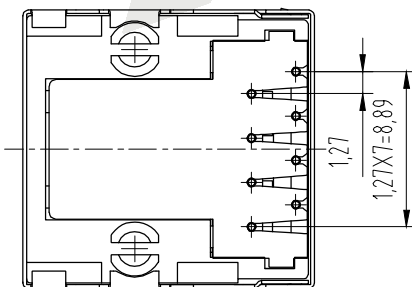
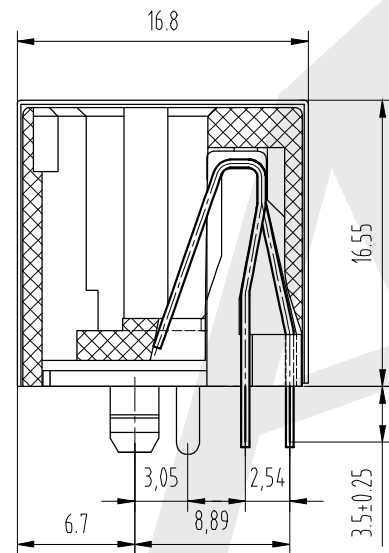
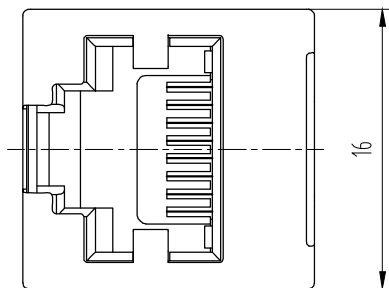
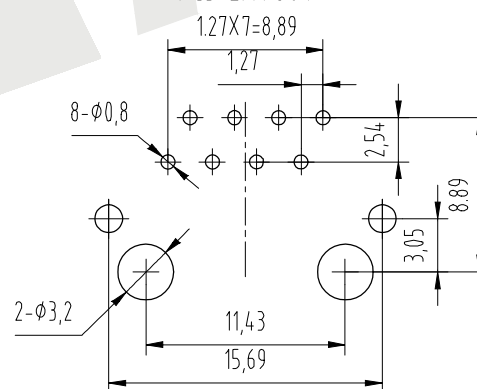


HSF



PCB LAYOUT



PCB LAYOUT/TOP VIEW

NOTES:

MATERIAL:

- 1. HOUSING MATERIAL :GLASS FILLED POYESTER UL94V-0.
- 2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.3mm
- 3. PLATING :SELECTING GOLD PLATING 1μ~50μ"OVER NICKEL IN CONTACT AREA. 150μ" TIN PLATIN.OVER NICKEL IN SOLDER AREA
- 4. SHIELD :0.2mmTHICKNESS COPPER WITH NICKEL PLATEI

ELECTRICAL

- 1. VOLTAGE RATING :125VAC RMS
- 2. CURRENT RATING :1.5AMP
- 3. CONTACT RESISTANCE:30 MILLIOHMS MAX
- 4. INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
- 5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL

- 1. DURRABILITY :750 CYCLES MIN
- 2. PCB RETENTTON PRB-SOLDER :1 LB MIN

REVIENVIRONMENTAL

- 1. STORAGE :-40° C TO 85° C
- 2. OPERATION :0° C TO 70° C

Order code:

ATRJ5222 - 8P - 8C - X - D - A - D

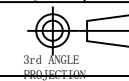
① ② ③ ④ ⑤ ⑥ ⑦

- ① SERIES NO: ⑤ Shield
- ② NUMBER OF POSITIONS (8P, 6P, 4P) A:W/O Shield
- ③ NUMBER OF CONTACTS (8C, 6C, 4C) B:Half Shield
- ④ Contact Plating C:Shield W/Eml
- D:Shield W/O Eml
- ⑥ Ports
- A:1X1P
- B:1X2P
- C:1X4P
- D:1X5P
- E:1X6P
- F:1X8P
- ⑦ PCB layout style:
- A:TYPE 1 front legs 3.05
- B:TYPE 1 front legs 3.68
- C:TYPE 1 front legs 4.57
- D:TYPE 2 Back legs 3.05
- E:TYPE 2 Back legs 3.68
- F:TYPE 2 Back legs 4.57

Unless Otherwise specified tolerance

X. ±0.35 X.XX: ±0.20  
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm  
DRAW: Wu Sai DATE: 26/07/2019  
CHECK: BobYang DATE: 26/07/2019



**Antenk**® ANTENK ELECTRONICS CO., LTD  
Http://www.antenk.com  
E-mail:sales@antenk.com

TITLE: Modular Jack Top entry 3.05, 8P8C, 1X1Port Full shielded

DRAWING NO: ATRJ5222-8P8C-X-D-A-D

PRODUCT NO: ATRJ5222-8P8C-X-D-A-D

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		